

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOMOTSUGU AOYAMA	09/15/2016
AKIRA SUGAWARA	09/15/2016
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15278340
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DATE SIGNED:	09/28/2016
Total Attachments: 2	
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ASSIGNMENT

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, We, the undersigned, Tomotsugu Aoyama, a citizen of Japan and a resident of c/o DOWA METALTECH CO., LTD., 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan, and Akira Sugawara, a citizen of Japan and a resident of c/o DOWA METALTECH CO., LTD., 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan, hereby sell, assign and transfer to DOWA METALTECH CO., LTD., a corporation of Japan, having a place of business at 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-0021, Japan, its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the following application for United States Letters Patent:

Serial No.:

Filing Date:

Title: HEAT RADIATING PLATE AND
METHOD FOR PRODUCING SAME

Inventors: Tomotsugu Aoyama et al.

Attorney's Docket No. 16-401

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said

improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

(L.S.) Tomotsugu Aoyama
Tomotsugu Aoyama

September 15, 2016
(Date)

(L.S.) Akira Sugawara
Akira Sugawara

September 5, 2016
(Date)